



SMC430

- SMD LED
- 430 nm, 18 mW
- Chip: InGaN, 350 x 350 μm , 1 pc.
- SMD package, Ceramic, 3.0 x 2.0 x 1.1 mm
- Viewing Angle: 112°



Description

SMC430 is a surface mount InGaN LED with a typical peak wavelength of **430 nm** and radiation of **18 mW**. It comes in SMD package (ceramic) and is sealed with silicone or epoxy resin.

Maximum Ratings ($T_{\text{CASE}}=25^{\circ}\text{C}$)

Parameter	Symbol	Values		Unit
		Min.	Max.	
Power Dissipation	P_D		200	mW
Forward Current	I_F		50	mA
Pulse Forward Current *1	I_{FP}		100	mA
Reverse Voltage	V_F		5	V
Thermal Resistance	R_{THJA}		80	K/W
Junction Temperature	T_J		120	$^{\circ}\text{C}$
Operating Temperature	T_{CASE}	- 40	+ 100	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	- 40	+ 100	$^{\circ}\text{C}$
Lead Solder Temperature *2	T_{SLD}		+ 250	$^{\circ}\text{C}$

*1 duty=1%, pulse width = 10 μs

*2 must be completed within 3 seconds

Electro-Optical Characteristics ($T_{\text{CASE}}=25^{\circ}\text{C}$)

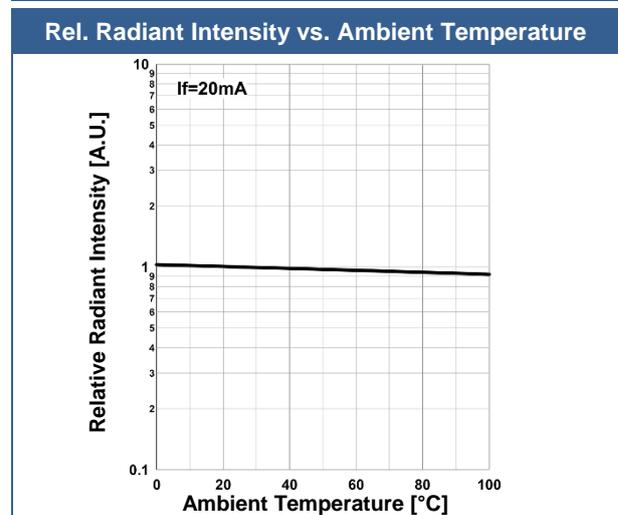
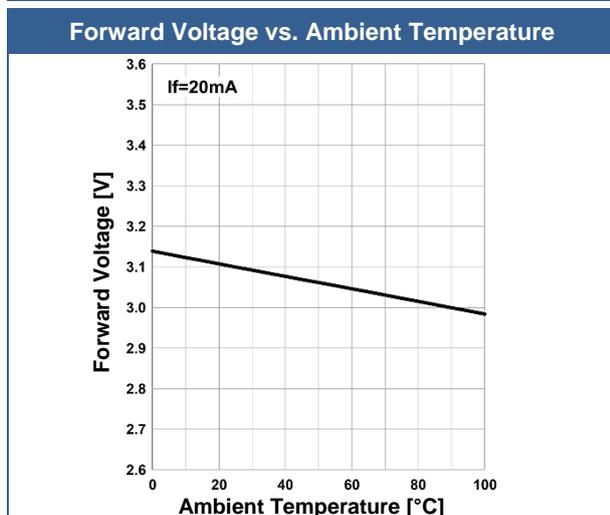
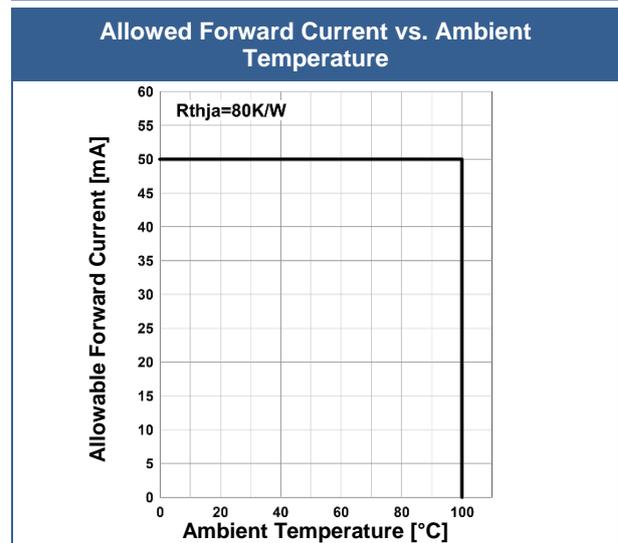
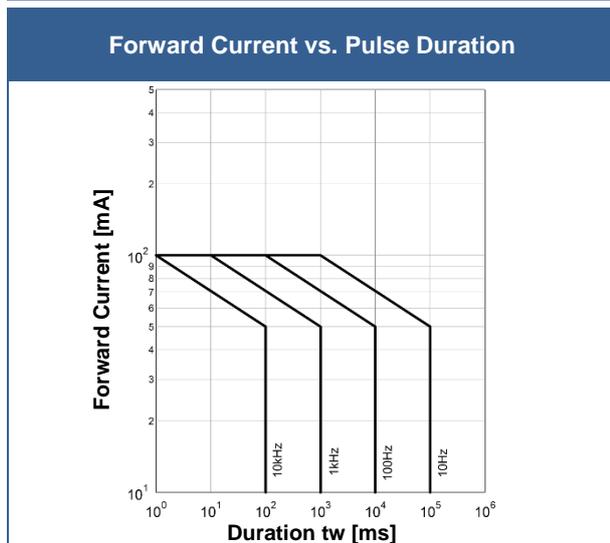
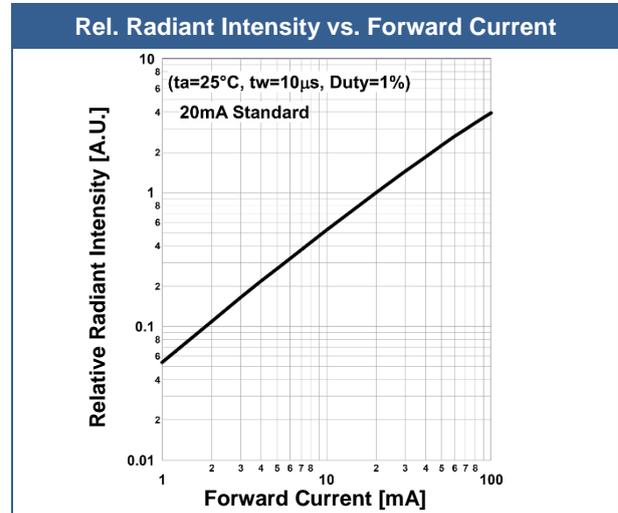
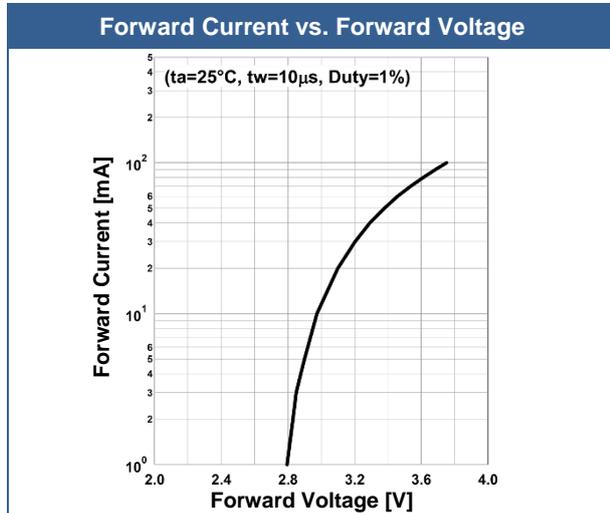
Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Peak Wavelength	λ_P	$I_F=20\text{mA}$	420		440	nm
Dominant Wavelength	λ_D	$I_F=20\text{mA}$		437		nm
Half Width	$\Delta\lambda$	$I_F=20\text{mA}$		16		nm
Forward Voltage	V_F	$I_F=20\text{mA}$		3.1	4.0	V
		$I_{FP}=100\text{mA}$		3.8		
Radiated Power *	P_O	$I_F=20\text{mA}$		18		mW
		$I_{FP}=100\text{mA}$		70		
Radiant Intensity	I_E	$I_F=20\text{mA}$		5.3		mW/sr
		$I_{FP}=100\text{mA}$		20		
Luminous Flux	Φ_V	$I_F=20\text{mA}$		250		mlm
Viewing Angle	φ	$I_F=20\text{mA}$		120		deg.
Rise Time	t_r	$I_F=20\text{mA}$		20		ns
Fall Time	t_f	$I_F=20\text{mA}$		20		ns

*1 measured by S3584-08

*2 measured by CIE127-2007 Condition B

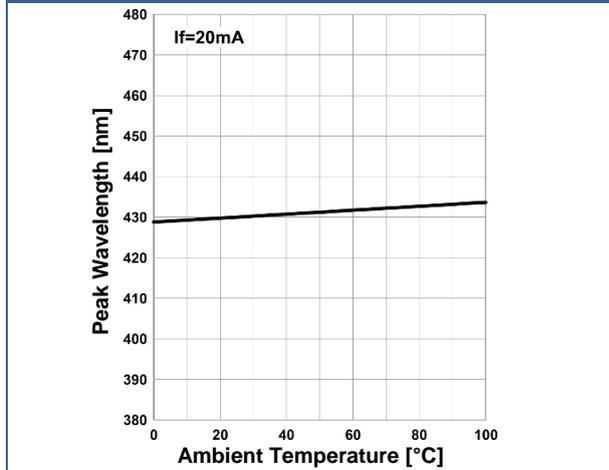


Typical Performance Curves

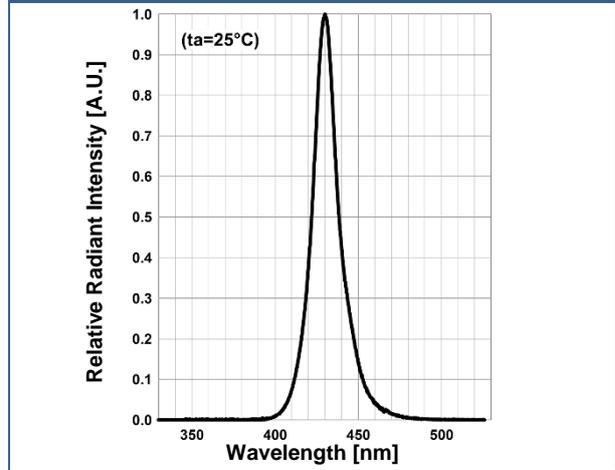




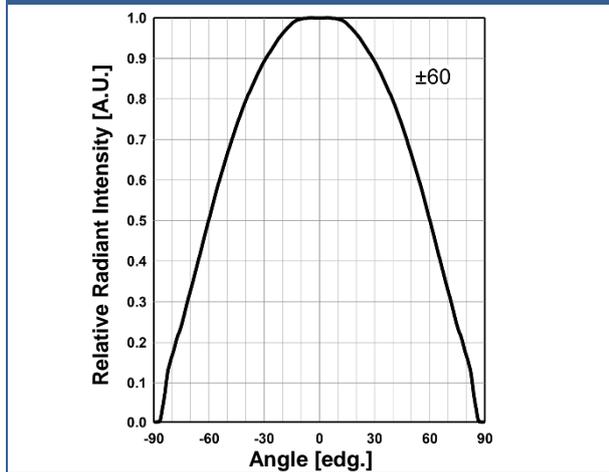
Peak Wavelength vs. Ambient Temperature



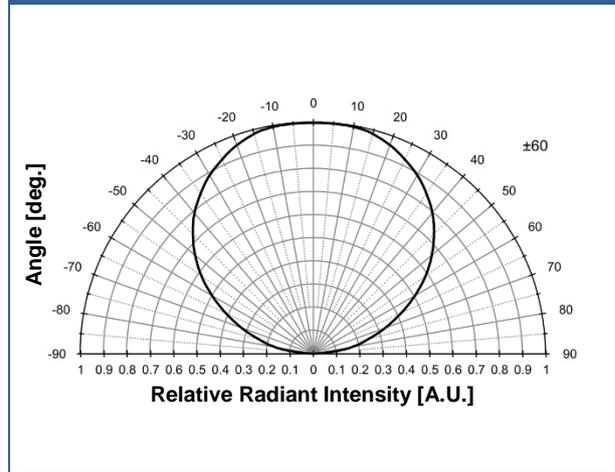
Relative Spectral Emission



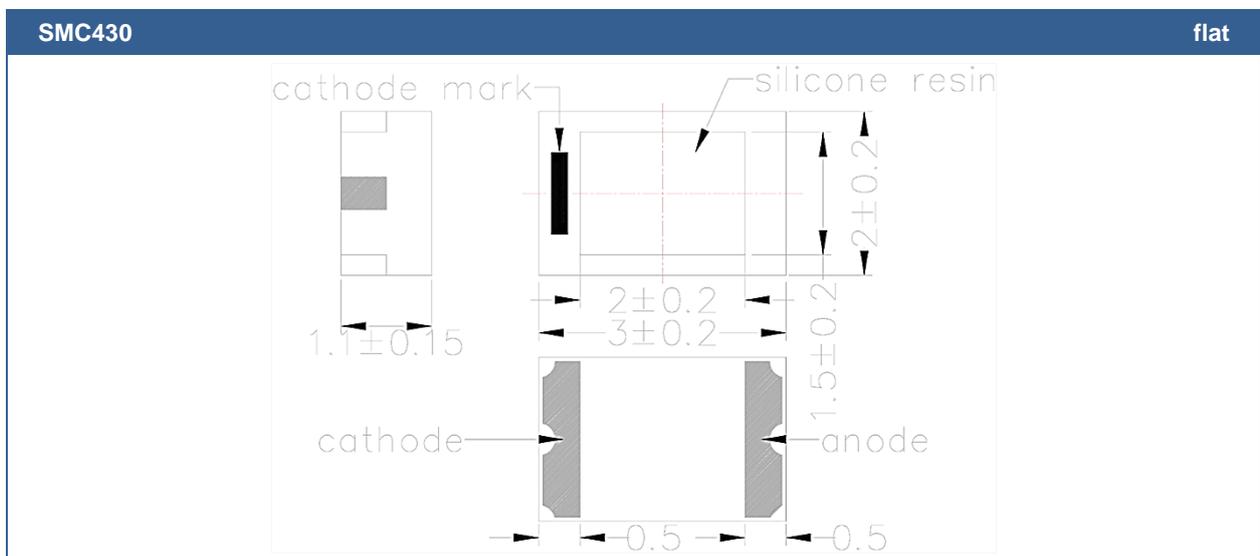
Radiation Characteristics



Radiation Characteristics



Outline Dimensions



All Dimensions in mm



Precautions

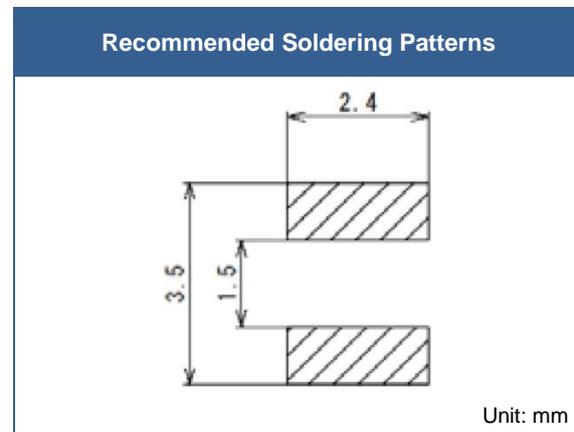
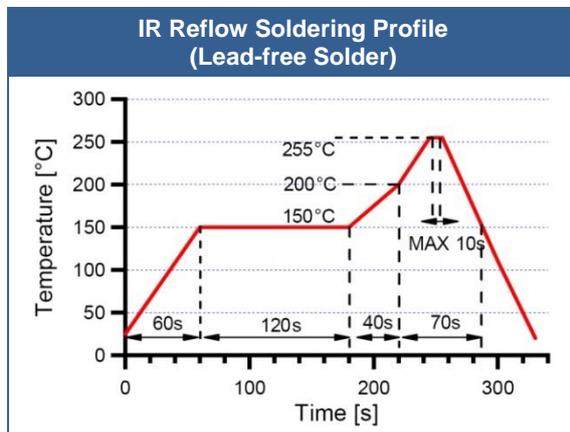
Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guaranteed.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroform, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

Those LEDs do emit **invisible light**, which is invisible and may cause cancer. Do avoid exposure to the emitted light. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.



Revisions History

Rel.	Rel. Date	Chapter	Modification	Page
A2	2022-07-06	-	Initial release	-

© All Rights Reserved

The above specifications are for reference purpose only and subjected to change without prior notice